

MICROELECTRONIC INTERCONNECT MATERIALS

Mountain Ridge Business Park, Unit B12

1248 Sussex Turnpike, Randolph, New Jersey 07869-2908 Phone: 973.895-3600 Fax: 973.895-3617 www.koartan.com

Distributed in the UK, Ireland & Scandinavia by: Inseto, Tel: +44 (0)1264 334505 www.inseto.co.uk

REV. 071502

Technical Information

5807 Multilayer Dielectric

The 5807 dielectric composition was developed as a general purpose insulation material for high density multilayered circuitry. It provides excellent via resolution capability and is compatible with silver-based, gold-based, and mixed metal conductor systems. The 5807 dielectric is a crystallizing composition, thus allowing resistor firing and component attachment on top of it. It does not contain

lead or highly toxic organic solvents. Key features include:

- Wide latitude in the selection of conductor metallurgies.
- Excellent via resolution.
- Dense, hermetic, crystallizing composition.
- Firing in 36-60 minute profiles.
- Resistor firing, soldering, and wire bonding capability.

TYPICAL FIRED FILM CHARACTERISTICS(1)

FIRED THICKNESS 36-48 im VIA REPOLUTION⁽²⁾ 200 im (0.008") DIELECTRIC CONSTANT(3) 7-10 DIMIDATION FACTOR < .2% @ 1KHz Injulation Rejistance (IR) > 10 12 Ohms @ 100VDC DIELECTRIC /TRENCTH > 1000 VDC/mil CAMBER < .003"/inch 250 microns thick

- (1) Typical properties are based on testing of several batches under various processing conditions. They are not intended as specification limits.
- (2) Using 325 mesh screen
- (3) The electrical results are based on 0.350" x 0.600" capacitors fabricated with 5807 dielectric and 6120 silver pastes. Two and three layers of dielectric were utilized to achieve the recommended fired film thickness.

COMPOSITION PROPERTIES

VICEOITY: 280 + 30 Kcps, when measured with Brookfield HBT, Spindle #14, utility cup, 10 rpm, 25 C.

≠DECIFIC GRAVITY: 1.80 – 2.20 g/cm³

RECOMMENDED THINNER: KOARTAN A-1039

RECOMMENDED PROCESSING PROCEDURE

Printing: For best results, three separate print/dry/fire operations with 325 mesh stainless steel screen using 10-15 im emulsion and 45 degree angle is recommended. Other mesh counts, 200-250, and emulsion thicknesses, 5-25 im, may be used for special applications. A class 10,000 or better clean room is required if only two layers of dielectric are to be used.

To ensure excellent via resolution and good leveling, the 5807 possesses a special rheology. Use a screen with good tension and allow at least 45 mils of break away to avoid screen popping. Depending on the print area, squeegee speeds of up to 6 inches/sec may be utilized.

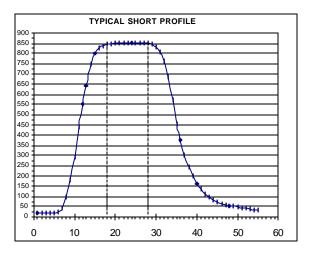
Coverage is approximately 120 cm² per layer, when utilizing 325 mesh screen and a wet print thickness of about 35 im.

Drying: Wet prints should be allowed to level for 5-10 minutes prior to drying. Dry for 10-15 minutes in a convection oven or belt dryer at 125°C-150°C.

Firing: Firing in air using a belt furnace and a 36-60 minute profile, with 10 minutes at a peak temperature of 850°C, is recommended. Air flow rates must be optimized to ensure that the products of binder burnoff discharge properly and create a fully oxidizing atmosphere in the muffle.

Storage and Shelf Life: Store in tightly capped containers at room temperature. Shelf life is 6 months for unopened jars. Thorough mixing of the paste before each use is recommended. Under ordinary conditions of storage and use the product should not require thinning. However, solvent lost

during extended printing runs may be replaced by incorporating up to 0.5% of Koartan A-1039 thinner.



Other System Components:

	<u>Silver-Based</u>	<u>Gold-Based</u>
Inner Conductor	6120 (100% Ag)	4100 (100% Au)
Via Fill	6101	4101
Top Conductor	6261 (6:1 Ag:Pd) 6231 (3:1 Ag:Pd) 6493 (Ag:Pd:Pt)	4100 4225 4296
Resistor	7600 Series	7600 Series

The information presented herein is based on data believed to be dependable and is accurate and reliable to the best of our knowledge and belief, but not guaranteed to be so. Koartan Company assumes no liability arising from the use of this product or the information provided herein. Nothing herein is to be construed as recommending any practice or any product in violation of any patent or in violation of any law or regulation.